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MOSFET - SiC Power, Single N-Channel, TO247-4L 650 V, 12 mΩ, 142 A

NTH4L015N065SC1

Features

- Typ. $R_{DS(on)} = 12 \text{ m}\Omega$ @ $V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 15 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge (Q_{G(tot)} = 283 nC)
- High Speed Switching with Low Capacitance ($C_{oss} = 430 \text{ pF}$)
- 100% Avalanche Tested
- $T_J = 175^{\circ}C$
- These Devices are Pb-Free and are RoHS Compliant

Typical Applications

- SMPS (Switching Mode Power Supplies)
- Solar Inverters
- UPS (Uninterruptable Power Supplies)
- Energy Storages

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	650	V
Gate-to-Source Voltage			V_{GS}	-8/+22	V
	Recommended Operation Values of Gate-to-Source Voltage		V_{GSop}	-5/+18	V
Continuous Drain Current (Note 1)	Steady T _C = 25°C		I _D	142	Α
Power Dissipation (Note 1)			P _D	500	W
Continuous Drain Current (Note 1)	Steady State	T _C = 100°C	I _D	100	Α
Power Dissipation (Note 1)			P _D	250	W
Pulsed Drain Current (Note 2)	T _C = 25°C		I _{DM}	483	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	114	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 13 A, L = 1 mH) (Note 3)			E _{AS}	84	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			TL	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

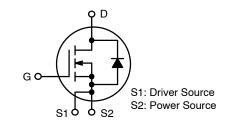
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. EAS of 84 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 13 A, V_{DD} = 50 V, V_{GS} = 18 V.



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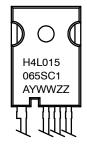
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
650 V	18 mΩ @ 18 V	142 A	



N-CHANNEL MOSFET



MARKING DIAGRAM



H4L015065SC1 = Specific Device Code

A = Assembly Location

Y = Year

WW = Work Week

ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping		
NTH4L015N065SC1	TO247-4L	30 Units / Tube		

THERMAL CHARACTERISTICS

Parameter		Max	Unit
Junction-to-Case - Steady State (Note 1)		0.3	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{ hetaJA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		650	_	_	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 20 mA, referenced to 25°C		-	0.12	-	V/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C	-	_	10	μΑ
		V _{DS} = 650 V	T _J = 175°C	-	_	1	mA
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +22/-8 \text{ V}, V_{DS}$	= 0 V	-	_	250	nA
ON CHARACTERISTICS (Note 2)					•		
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 25 \text{ m}$	A	1.8	2.5	4.3	V
Recommended Gate Voltage	V_{GOP}			-5	-	+18	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 75 A	, T _J = 25°C	_	15	-	mΩ
		V _{GS} = 18 V, I _D = 75 A	, T _J = 25°C	_	12	18	
		V _{GS} = 18 V, I _D = 75 A	, T _J = 175°C	_	16	-	
Forward Transconductance	9FS	V _{DS} = 10 V, I _D = 75 A		_	47	-	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE					l l	
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 325 V		_	4790	-	pF
Output Capacitance	C _{OSS}			_	430	-	
Reverse Transfer Capacitance	C _{RSS}			_	33	-	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = -5/18 V, V _{DS} = 520 V, I _D = 75 A		_	283	-	nC
Gate-to-Source Charge	Q _{GS}			_	72	-	
Gate-to-Drain Charge	Q_{GD}			_	64	-	
Gate-Resistance	R_{G}			-	1.6	_	Ω
SWITCHING CHARACTERISTICS	•						
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -5/18 \text{ V},$		-	23	-	ns
Rise Time	t _r	V_{DS} = 400 V, I_D = 75 A, R_G = 2.2 Ω inductive load		-	26	_	
Turn-Off Delay Time	t _{d(OFF)}			-	49	-	
Fall Time	t _f			-	9.6	_	
Turn-On Switching Loss	E _{ON}			-	167	_	μJ
Turn-Off Switching Loss	E _{OFF}			-	276	_	
Total Switching Loss	E _{tot}		-	443	-		
SOURCE-DRAIN DIODE CHARACTERIST							
Continuous Source-Drain Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}\text{C}$)	-	-	114	Α
Pulsed Source-Drain Diode Forward Current (Note 2)	I _{SDM}			-	-	483	
Forward Diode Voltage	V_{SD}	V _{GS} = -5 V, I _{SD} = 75	A, T _J = 25°C	-	4.8	_	V

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
SOURCE-DRAIN DIODE CHARACTERISTICS							
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/18 \text{ V}, I_{SD} = 75 \text{ A},$	-	28	_	ns	
Reverse Recovery Charge	Q _{RR}	$dI_S/dt = 1000 A/\mu s$	-	234	-	nC	
Reverse Recovery Energy	E _{REC}		-	23	-	μJ	
Peak Reverse Recovery Current	I _{RRM}		_	16	_	Α	
Charge time	Ta		_	17	_	ns	
Discharge time	Tb		-	11	_	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

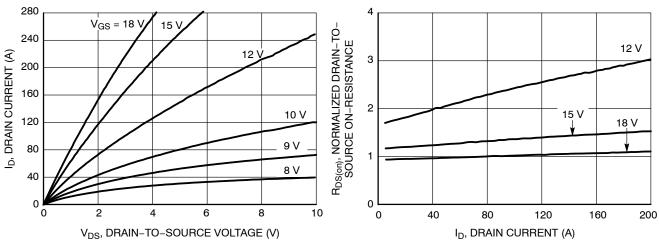


Figure 1. On-Region Characteristics

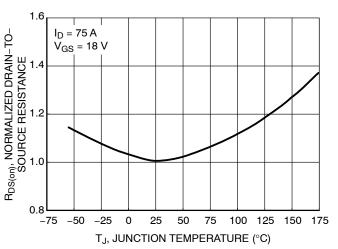


Figure 3. On–Resistance Variation with Temperature

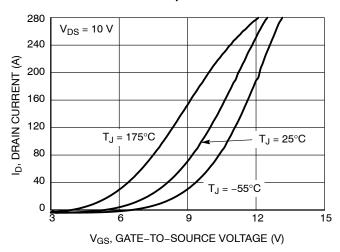


Figure 5. Transfer Characteristics

Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

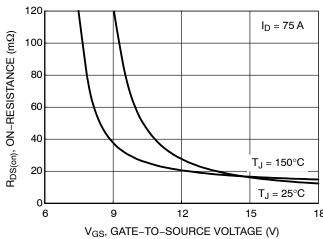
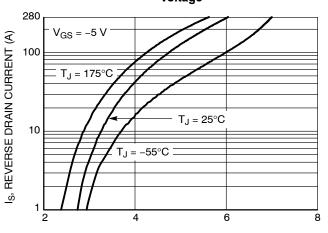


Figure 4. On-Resistance vs. Gate-to-Source Voltage



V_{SD}, BODY DIODE FORWARD VOLTAGE (V)

Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS

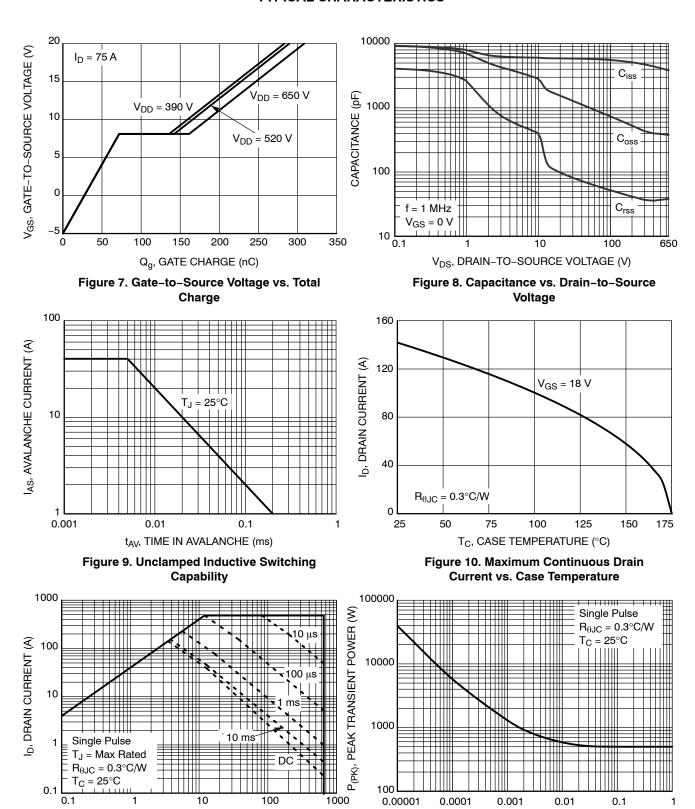


Figure 12. Single Pulse Maximum Power
Dissipation

t, PULSE WIDTH (sec)

V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V)

Figure 11. Safe Operating Area

TYPICAL CHARACTERISTICS

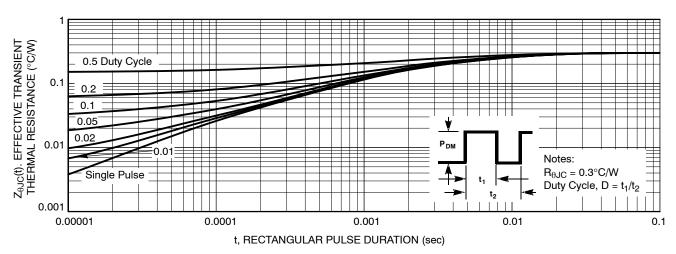
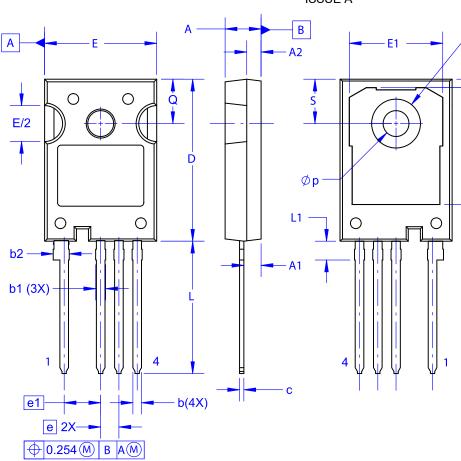


Figure 13. Junction-to-Case Thermal Response

PACKAGE DIMENSIONS

TO-247-4LD CASE 340CJ ISSUE A



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MILLIMETERS					
ווועו	MIN	NOM	MAX			
Α	4.80	5.00	5.20			
A1	2.10	2.40	2.70			
A2	1.80	2.00	2.20			
b	1.07	1.20	1.33			
b1	1.20	1.40	1.60			
b2	2.02	2.22	2.42			
С	0.50	0.60	0.70			
D	22.34	22.54	22.74			
D1	16.00	16.25	16.50			
D2	0.97	1.17	1.37			
е	2.54 BSC					
e1	5.08 BSC					
Е	15.40	15.60	15.80			
E1	12.80	13.00	13.20			
E/2	4.80	5.00	5.20			
L	18.22	18.42	18.62			
L1	2.42	2.62	2.82			
р	3.40	3.60	3.80			
p1	6.60	6.80	7.00			
Q	5.97	6.17	6.37			
S	5.97	6.17	6.37			

Ø**p1**

D1

D2

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